

**VALTRON® - Ingot Mounting Adhesive System****VALTRON AD 1230-A RESIN  
VALTRON AD 3831-BR HARDENER****Features**

- ⇒ 35-40 min. cure time at room temperature
- ⇒ Color coded mixing system
- ⇒ Patented formulation reduces thermal stress during cure
- ⇒ Easily debonded with VALTRON alkaline detergent
- ⇒ Effective with ID blade and wire slicing equipment
- ⇒ Available in various packaging systems

**Description**

The VALTRON Quick-Cure Adhesive Ingot Mounting Adhesive is a two component epoxy system consisting of VALTRON AD 1230-A resin and VALTRON AD 3831-BR hardener. The cure time for the VALTRON adhesive is app. 35-40 min. at room temperature. The fast curing adhesive system effectively adheres semiconductor and photovoltaic ingots to mounting fixtures and slicing beams. The VALTRON Quick-Cure adhesive provides excellent bonding.

**Typical Physical Properties**

Specific Gravity (@ 20° C):	AD 1230-A	1.21 g/cc
	AD 3831-BR	1.12 g/cc
Appearance (Color):	AD 1230-A	Grey
	AD 3831-BR	Red
Viscosity (Brookfield Model HTB):	AD 1230-A	30.000 - 40.000 cps @ 25° C
	AD 3831-BR	10.000 - 16.000 cps @ 25° C

**Packaging**

The VALTRON Quick Cure Adhesive system is available in:

- ⇒ 5 gallon pail
- ⇒ 4x1 gallon cases
- ⇒ 1 gallon container
- ⇒ 1 pint can
- ⇒ pre-measured syringe

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- Step 1** Thoroughly clean the surface of the ingot and the mounting fixture with a solvent.
- Step 2** Accurately weigh the two components into a mixing cup using 100 parts by weight of the resin, AD 1230-A and 45 parts by weight of the AD 3831-BR hardener.
- Step 3** Thoroughly mix the two adhesive components until a uniform color is achieved.
- Step 4** Apply a thin layer of the adhesive to the mounting fixture or slicing beam.
- Step 5** Place ingot on the mounting fixture and wipe off any excess adhesive.
- Step 6** Allow adhesive to cure for app. 40 min. at room temperature

**Removal/Demounting**

The VALTRON Quick Cure Ingot Mounting Adhesive is designed to temporarily bond ingots during the wafering process. The VALTRON Quick Cure adhesive needs to be removed from the sliced wafers. The unique properties of this adhesive system allow for removal of the adhesive using a heated VALTRON high pH alkaline detergent solution. This process allows the sliced wafers to be cleaned of adhesive, saw coolant and kerf in an easy procedure.

- Step 1** Prepare a 15.0% solution of the VALTRON SP 2500 alkaline detergent and heat to 80° C.
- Step 2** Place the sliced wafers in the heated VALTRON detergent solution.
- Step 3** The adhesive will be removed from the sliced wafers within 10-15 min. The removal time may vary depending on ingot surface conditions.
- Step 4** Thoroughly rinse the demounted wafers with deionized water.

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